SNx4LV02A Quadruple 2-Input Positive-NOR Gates

1 Features

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 6.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot) > 2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Live insertion, Partial Power Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model
  - 200-V Machine Model
  - 1000-V Charged-Device Model

2 Applications

- Handset: Smartphone
- Network Switch
- Health & Fitness / Wearables
- PDAs
- TV (LCD)
- Power Infrastructure

3 Description

The SNx4LV02A devices are quadruple 2-input positive-NOR gates designed for 2-V to 5.5-V V_{CC} operation.

The SNx4LV02A devices perform the Boolean function $Y = \overline{A + B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

Device Information(1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SNx4LV02A	VQFN (14)	3.50 mm x 3.50 mm
	SOIC (14)	8.65 mm × 3.91 mm
	SOP (14)	10.30 mm x 5.30 mm
	SSOP (14)	6.20 mm x 5.30 mm
	TSSOP (14)	5.00 mm x 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 Simplified Schematic

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

5 Revision History

Changes from Revision I (April 2005) to Revision K **Page**

- Added *Applications*, *Device Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Typical Characteristics*, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section. ... 1

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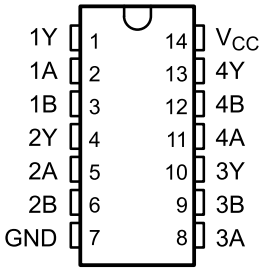
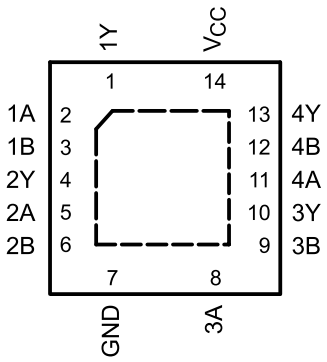
6 Pin Configuration and Functions

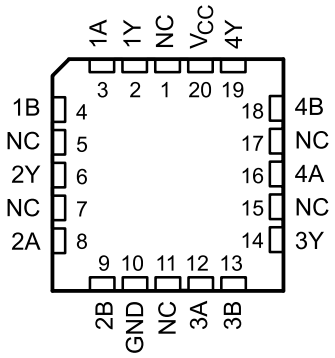
SN54LV02A . . . J OR W PACKAGE
SN74LV02A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)



SN74LV02A . . . RGY PACKAGE
(TOP VIEW)



SN54LV02A . . . FK PACKAGE
(TOP VIEW)



NC - No internal Connection

Pin Functions

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	1Y	O	1Y output
2	1A	I	1A input
3	1B	I	1B input
4	2Y	O	2Y output
5	2A	I	2A input
6	2B	I	2B input
7	GND	—	GND
8	3A	I	3A input
9	3B	I	3B input
10	3Y	O	3Y output
11	4A	I	4A input
12	4B	I	4B input
13	4Y	O	4Y output
14	V_{CC}	—	V_{CC}

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7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		–0.5	7	V
V_I	Input voltage range(2)		–0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)		–0.5	7	V
V_O	Output voltage range(2)(3)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–20	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current	V_O = 0 to V_{CC}		±25	mA
	Continuous current through V_{CC} or GND			±50	mA
T_{stg}	Storage temperature range		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This value is limited to 5.5-V maximum.

7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1)	±1500	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2)	±2000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

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7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

			SN54LV02A(2)		SN74LV02A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 2.3 V to 2.7 V	V_{CC} × 0.7		V_{CC} × 0.7		
		V_{CC} = 3 V to 3.6 V	V_{CC} × 0.7		V_{CC} × 0.7		
		V_{CC} = 4.5 V to 5.5 V	V_{CC} × 0.7		V_{CC} × 0.7		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		V_{CC} × 0.3		V_{CC} × 0.3	
		V_{CC} = 3 V to 3.6 V		V_{CC} × 0.3		V_{CC} × 0.3	
		V_{CC} = 4.5 V to 5.5 V		V_{CC} × 0.3		V_{CC} × 0.3	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	5.5	0	5.5	V
I_{OH}	High-level output current	V_{CC} = 2 V		–50		–50	μA
		V_{CC} = 2.3 V to 2.7 V		–2		–2	mA
		V_{CC} = 3 V to 3.6 V		–6		–6	
		V_{CC} = 4.5 V to 5.5 V		–12		–12	
I_{IH}	Low-level output current	V_{CC} = 2 V		50		50	mA
		V_{CC} = 2.3 V to 2.7 V		2		2	
		V_{CC} = 3 V to 3.6 V		6		6	
		V_{CC} = 4.5 V to 5.5 V		12		12	
Δt/Δv	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V		200		200	ns/V
		V_{CC} = 3 V to 3.6 V		100		100	
		V_{CC} = 4.5 V to 5.5 V		20		20	
T_A	Operating free-air temperature		–55	125	–40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).
(2) Product Preview.

7.4 Thermal Information

THERMAL METRIC(1)		SN74LV02A						UNIT
		D	DB	DGV	NS	PW	RGY	
		14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	97.5	109.5	133.3	92.2	125.1	59.0	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	58.7	62.1	55.6	49.8	53.7	72.5	
$R_{\theta JB}$	Junction-to-board thermal resistance	51.8	56.9	66.3	51.0	66.9	35.0	
Ψ_{JT}	Junction-to-top characterization parameter	22.6	22.6	7.8	15.7	7.6	3.9	
Ψ_{JB}	Junction-to-board characterization parameter	51.6	56.3	56.6	50.6	66.3	35.1	
$R_{\theta JC(bot)}$		–	–	–	–	–	15.4	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report (SPRA953).

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7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LV02A(1)			–40°C to 85°C SN74LV02A		–40°C to 125°C SN74LV02A		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	I_{OL} = –50 µA	2 V to 5.5 V	V_{CC} – 0.1			V_{CC} – 0.1		V_{CC} – 0.1		
	I_{OL} = –2 mA	2.3 V	2			2		2		
	I_{OL} = –6 mA	3 V	2.48			2.48		2.48		
	I_{OL} = –12 mA	4.5 V	3.8			3.8		3.8		
V_{OL}	I_{OL} = 50 µA	2 V to 5.5 V			0.1		0.1		0.1	V
	I_{OL} = 2 mA	2.3 V			0.4		0.4		0.4	
	I_{OL} = 6 mA	3 V			0.44		0.44		0.44	
	I_{OL} = 12 mA	4.5 V			0.55		0.55		0.55	
I_I	V_I = 5.5 V or GND	0 to 5.5 V			±1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5			20		20		20	µA
I_{off}	V_I or V_O = 0 to 5.5 V	0			5		5		5	µA
C_i	V_I = V_{CC} or GND	3.3 V		1.6			1.6		1.6	pF

(1) Product Preview.

7.6 Switching Characteristics, V_{CC} = 2.5 V ± 0.2 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV02A		–40°C to 85°C SN74LV02A		–40°C to 125°C SN74LV02A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	C_L = 15 pF		8.3(1)	12.4(1)	1(1)	15(1)	1	15	1	17.5	ns
			C_L = 50 pF		11(1)	16.1(1)	1	19	1	19	1	21.5	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

7.7 Switching Characteristics, V_{CC} = 3.3 V ± 0.3 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV02A		–40°C to 85°C SN74LV02A		–40°C to 125°C SN74LV02A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	C_L = 15 pF		5.6(1)	7.9(1)	1(1)	9.5(1)	1	9.5	1	11.5	ns
			C_L = 50 pF		7.6(1)	11.4(1)	1	13	1	13	1	15	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

7.8 Switching Characteristics, V_{CC} = 5 V ± 0.5 V

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV02A		–40°C to 85°C SN74LV02A		–40°C to 125°C SN74LV02A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	Y	C_L = 15 pF		3.9(1)	5.5(1)	1(1)	6.5(1)	1	6.5	1	8	ns
			C_L = 50 pF		5.3(1)	7.5(1)	1	8.5	1	8.5	1	10	

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested.

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7.9 Noise Characteristics(1)

V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C

PARAMETER		SN74LV02A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		–0.1	–0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3.2		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

7.10 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF,	f = 10 MHz	3.3 V	8.9	pF
				5 V	3	

7.11 Typical Characteristics

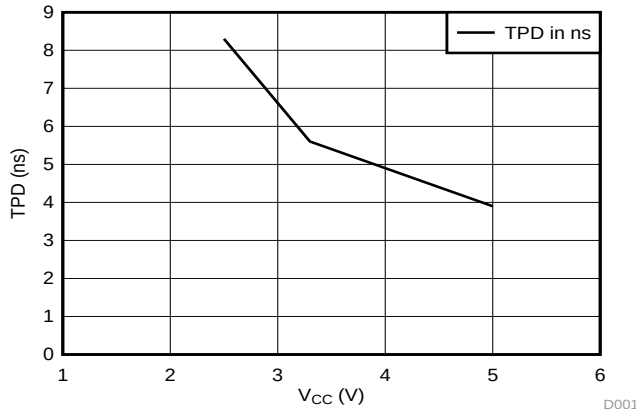


Figure 1. TPD vs Temperature

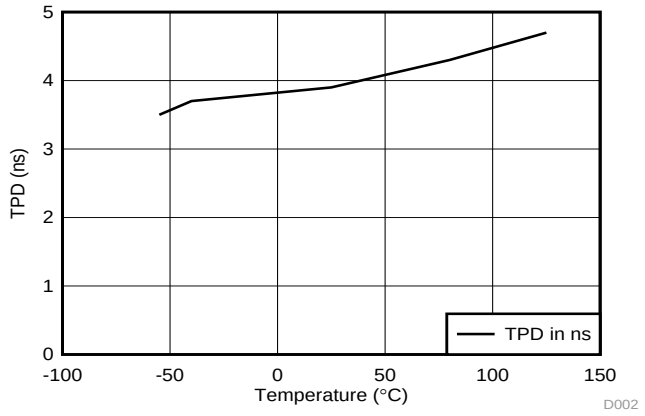
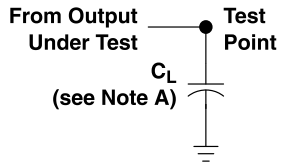
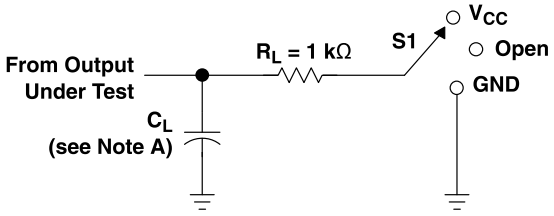


Figure 2. TPD vs V_{CC} at 25°C

8 Parameter Measurement Information

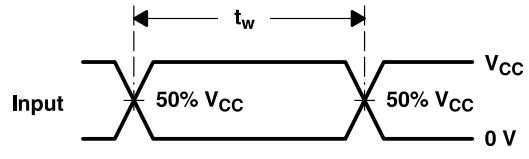


LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS

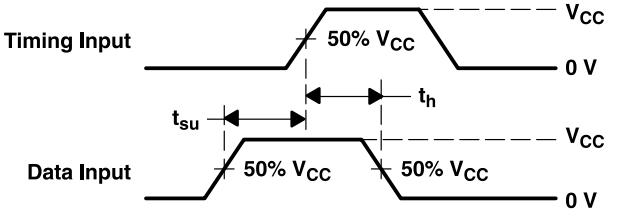


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

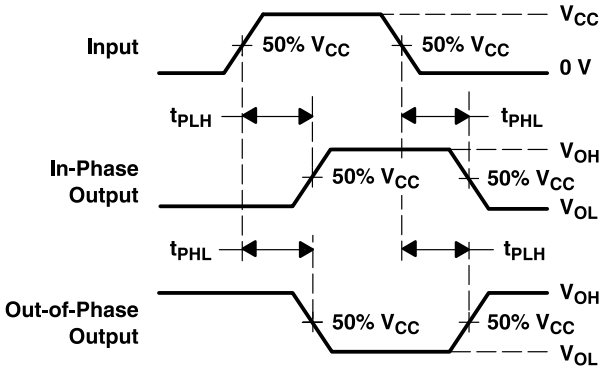
LOAD CIRCUIT FOR
3-STATE AND OPEN-DRAIN OUTPUTS



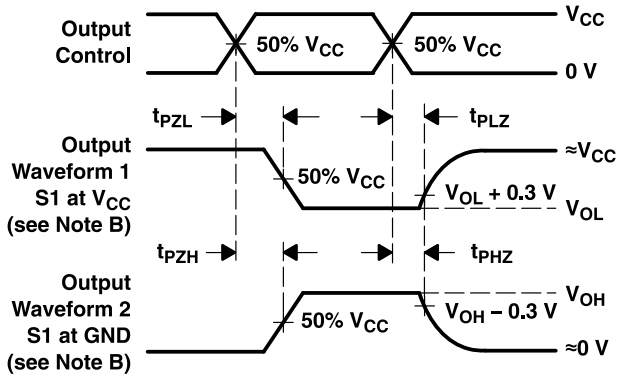
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
D. The outputs are measured one at a time, with one input transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PHL} and t_{PLH} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms

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9 Detailed Description

9.1 Overview

The SN74LV02A devices are quadruple 2-input positive-NOR gates designed for 2-V to 5.5-V V_{CC} operation.

The SN74LV02A devices perform the Boolean function $Y = \overline{A + B}$ or $Y = \overline{A} \bullet \overline{B}$ in positive logic.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

9.2 Functional Block Diagram

Figure 4. Logic Diagram (Positive Logic)

9.3 Feature Description

- Wide operating voltage range
  - Operates from 2 V to 5.5 V
- Allows down voltage translation
  - Inputs accept voltages to 5.5 V
- I_{off} feature allows voltages on the inputs and outputs when V_{CC} is 0 V

9.4 Device Functional Modes

Table 1. Function Table (Each Gate)

INPUT		OUTPUT
A	B	Y
H	X	L
X	H	L
L	L	H

10 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

10.1 Application Information

The SN74LV02A is a Low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs can accept voltages to 5.5 V at any valid V_{CC} making it Ideal for down translation.

10.2 Typical Application

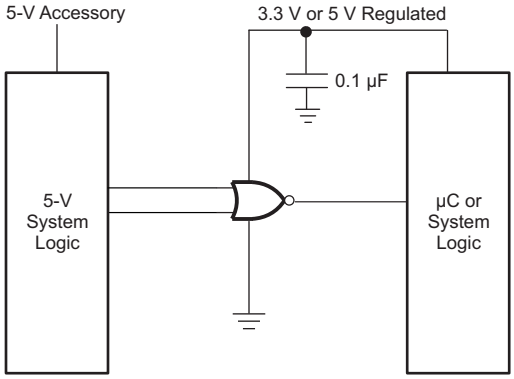

Figure 5. Typical Application Schematic

10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
   - For specified High and low levels, see V_{IH} and V_{IL} in the *Recommended Operating Conditions* table.
   - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}.
2. Recommend Output Conditions
   - Load currents should not exceed 25 mA per output and 50 mA total for the part.
   - Outputs should not be pulled above V_{CC}.

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Typical Application (continued)

10.2.3 Application Curves

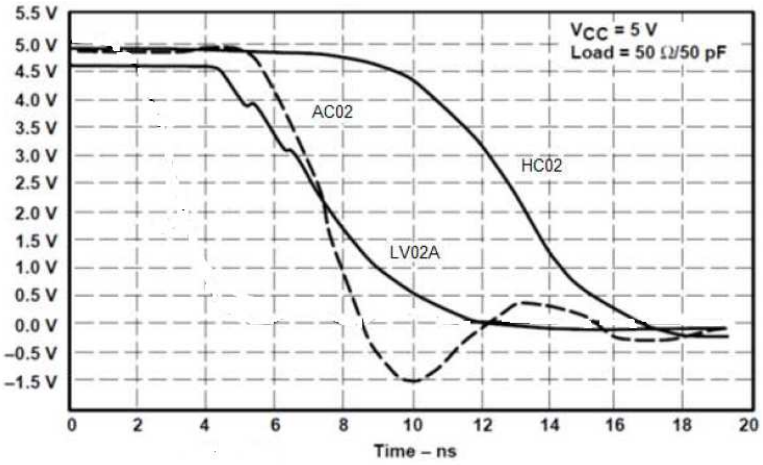

Figure 6. Typical Application Curve

11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1 µf capacitor is recommended and if there are multiple V_{CC} terminals then .01 µf or .022 µf capactior is recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1 µf and 1 µf capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

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12 Layout

12.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float. In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. It is generally OK to float outputs unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O's so they also cannot float when disabled.

12.2 Layout Example

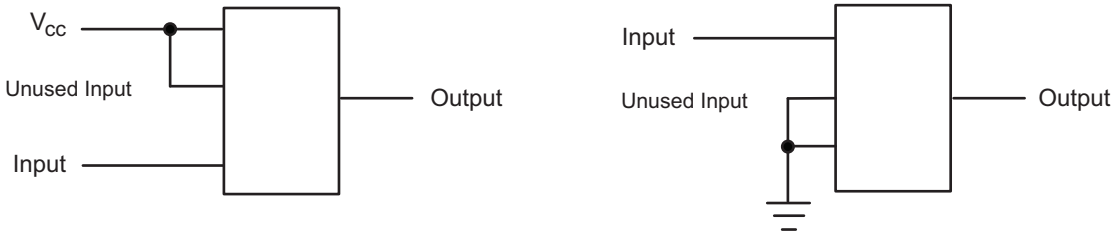

Figure 7. Layout Diagram

13 Device and Documentation Support

13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 2. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74LV02A	Click here	Click here	Click here	Click here	Click here

13.2 Trademarks

All trademarks are the property of their respective owners.

13.3 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

13.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

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14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV02AD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125	LV02A	
SN74LV02ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples
SN74LV02ADBRE4	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples
SN74LV02ADGVR	ACTIVE	TVSOP	DGV	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples
SN74LV02ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples
SN74LV02ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	74LV02A	Samples
SN74LV02APW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	LV02A	
SN74LV02APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples
SN74LV02APWT	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125	LV02A	
SN74LV02ARGYR	ACTIVE	VQFN	RGY	14	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LV02A	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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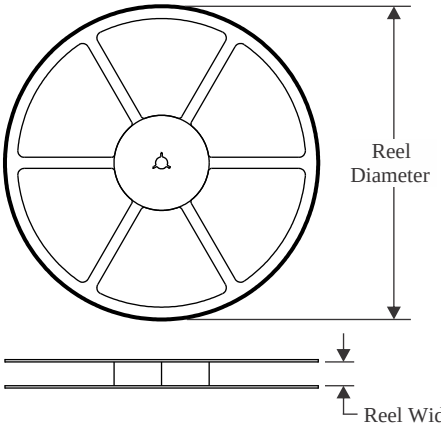
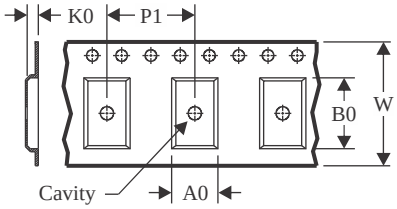
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

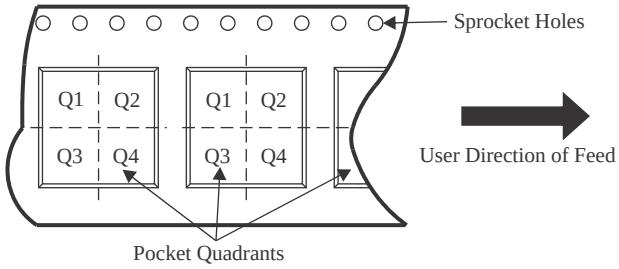


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

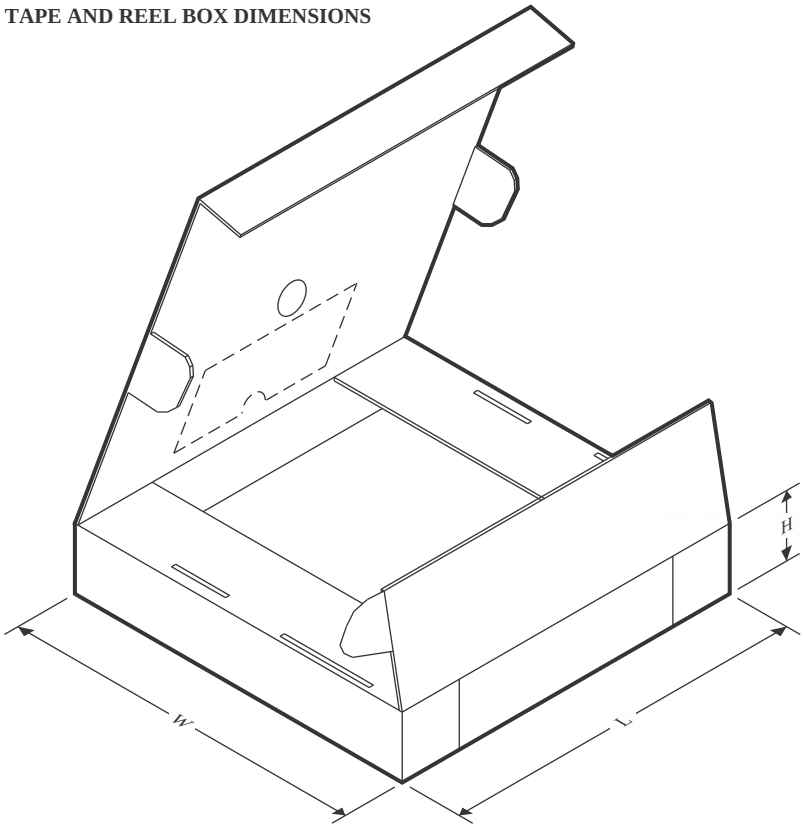
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV02ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV02ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV02ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV02ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV02APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV02APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV02ARGYR	VQFN	RGY	14	3000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

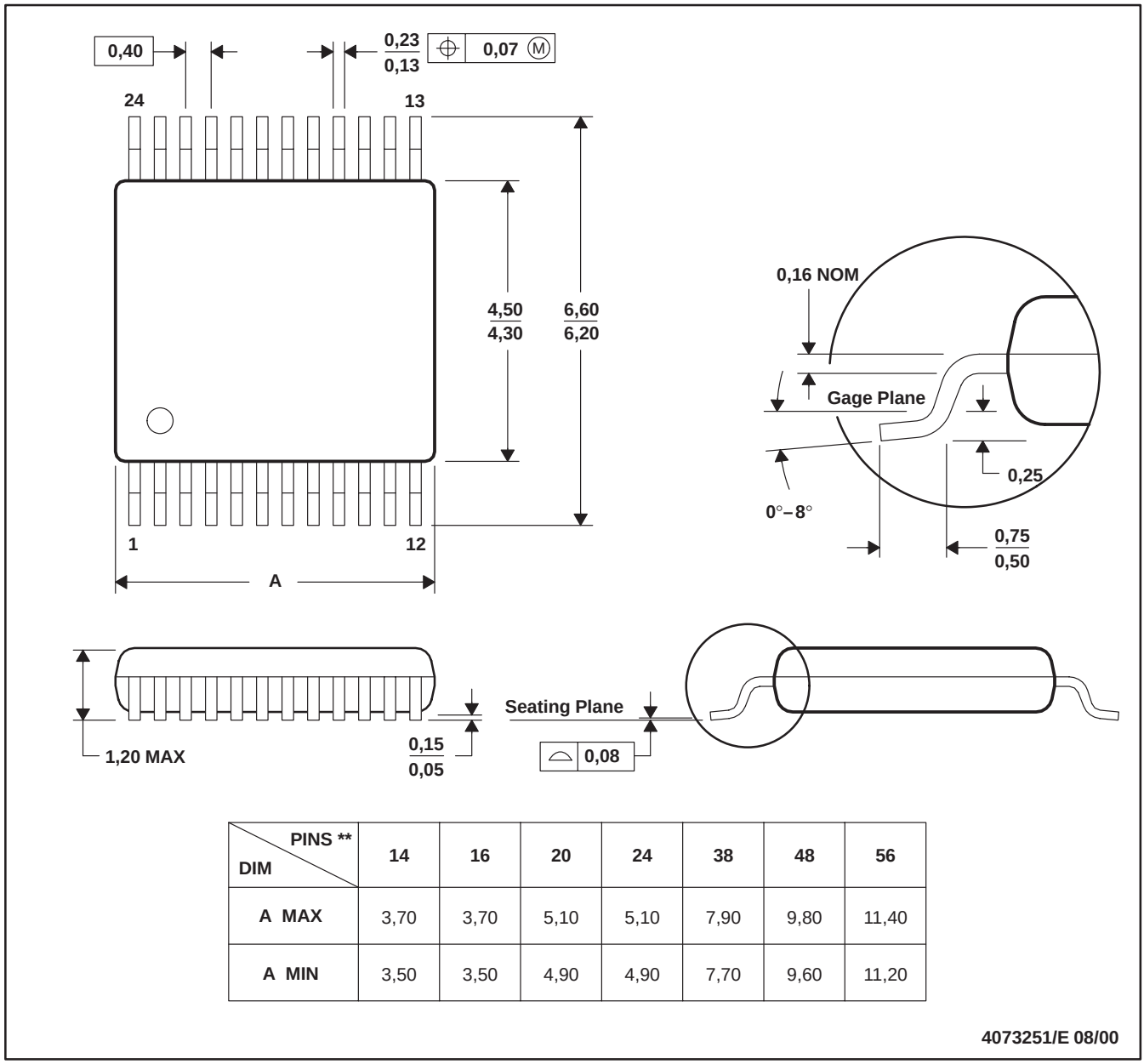


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV02ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74LV02ADGVR	TVSOP	DGV	14	2000	356.0	356.0	35.0
SN74LV02ADR	SOIC	D	14	2500	356.0	356.0	35.0
SN74LV02ANSR	SO	NS	14	2000	356.0	356.0	35.0
SN74LV02APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV02APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74LV02ARGYR	VQFN	RGY	14	3000	360.0	360.0	36.0

DGV (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN



DIM \ PINS **	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

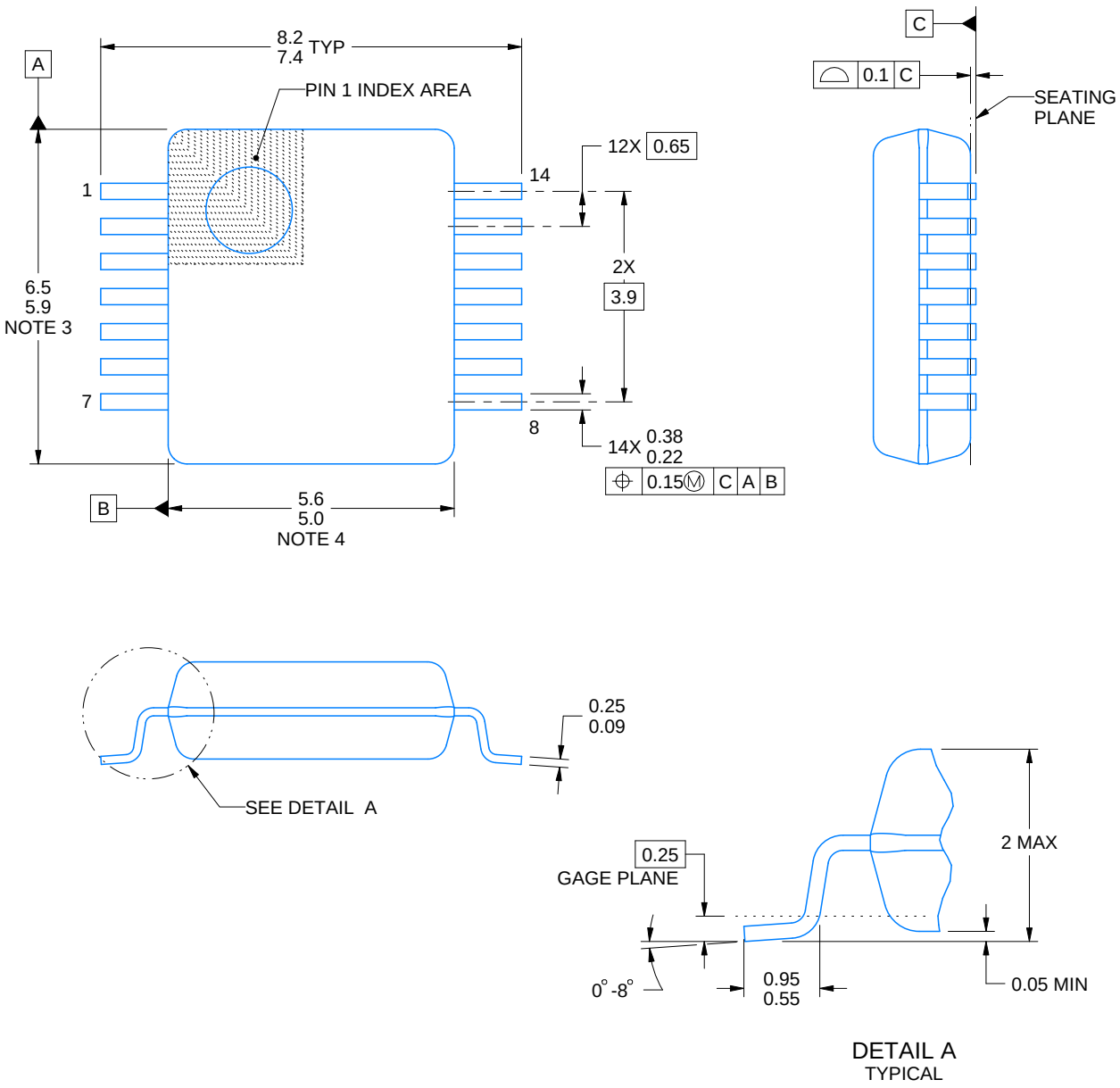
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

PACKAGE OUTLINE

DB0014A

SSOP - 2 mm max height

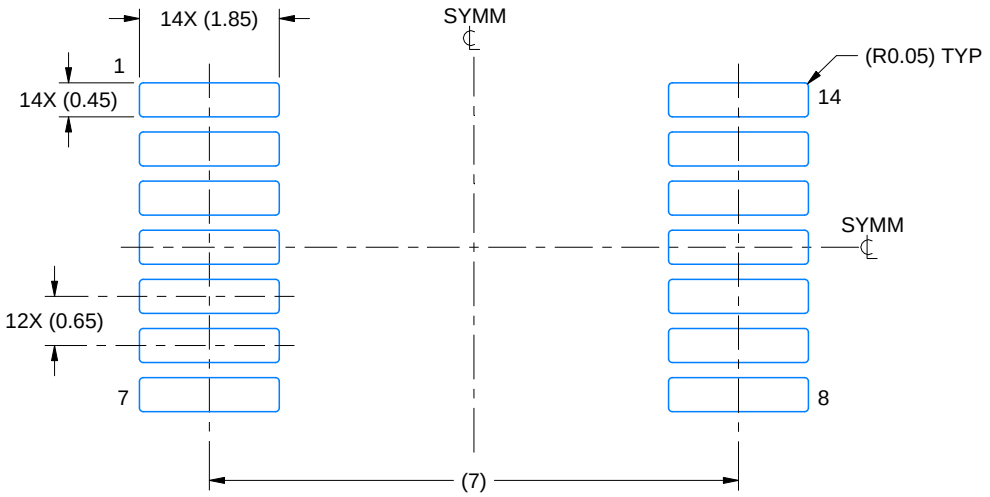
SMALL OUTLINE PACKAGE



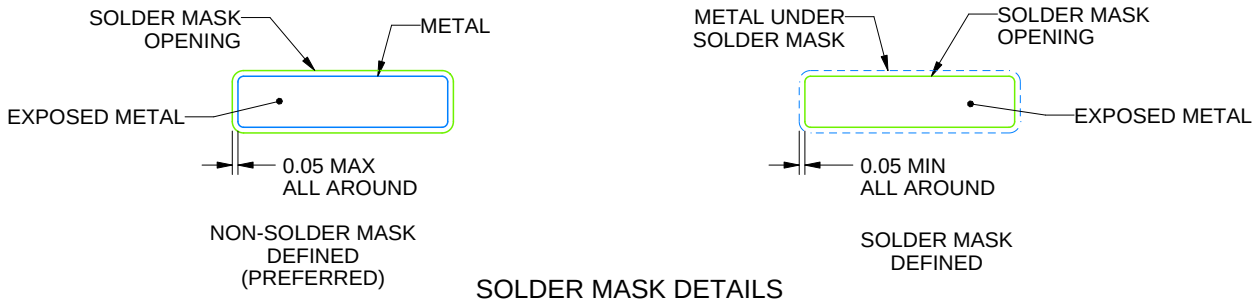
4220762/A 05/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

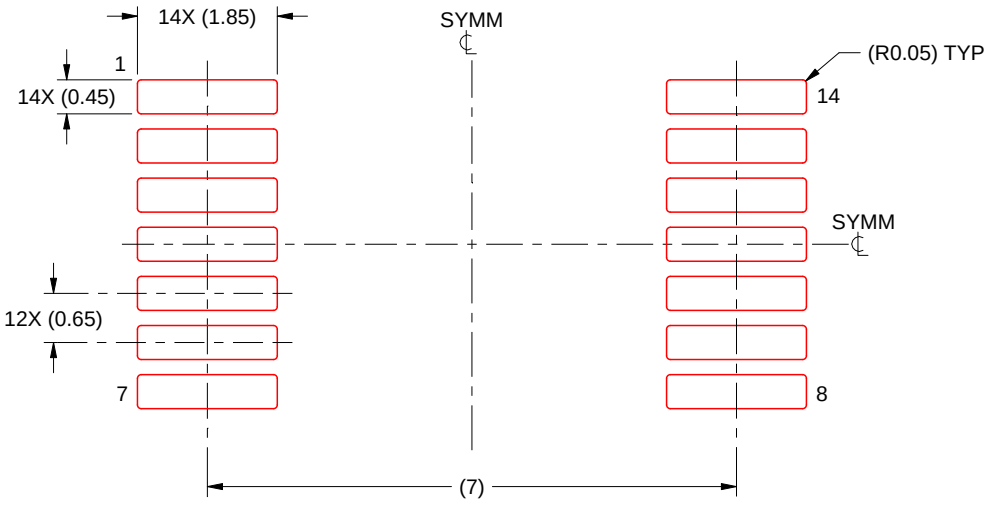


SOLDER MASK DETAILS

4220762/A 05/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

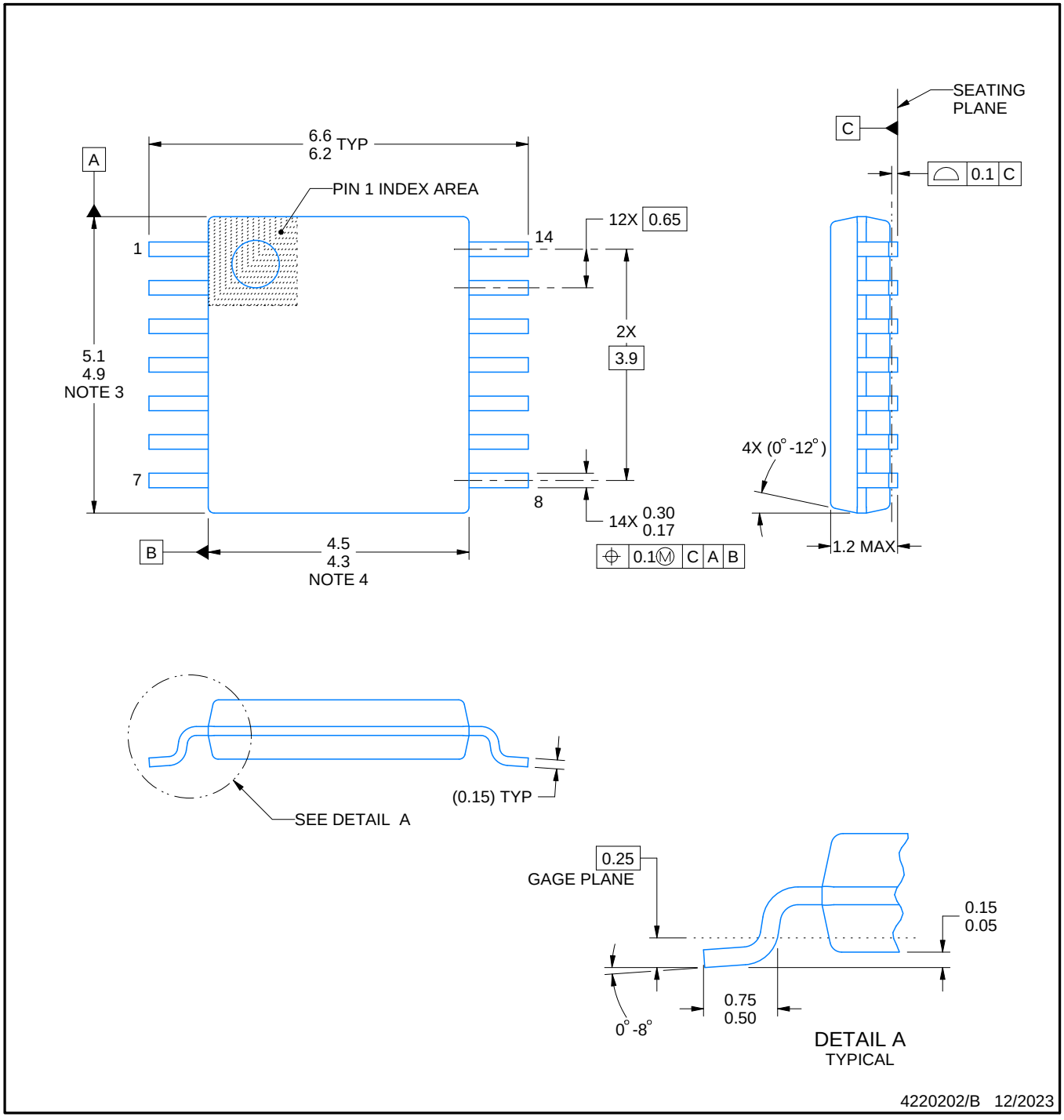
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0014A

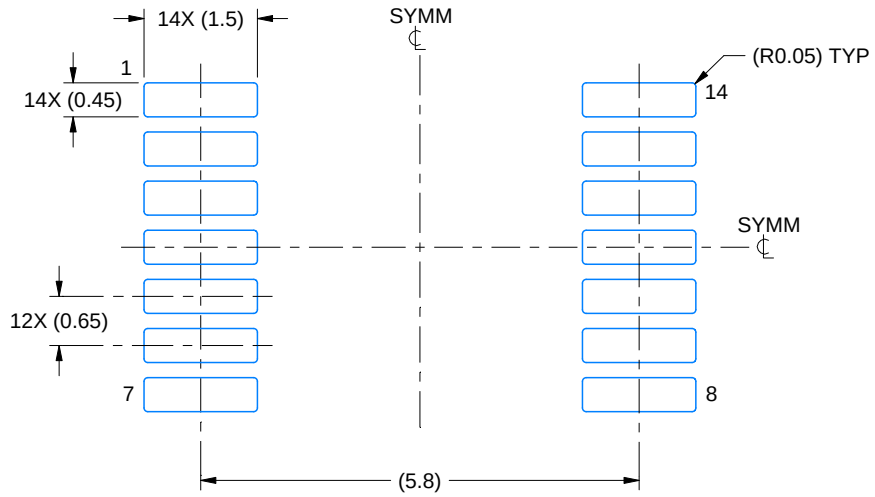
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

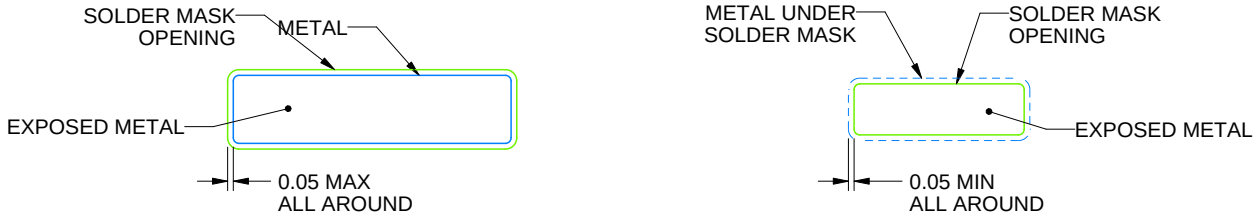


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

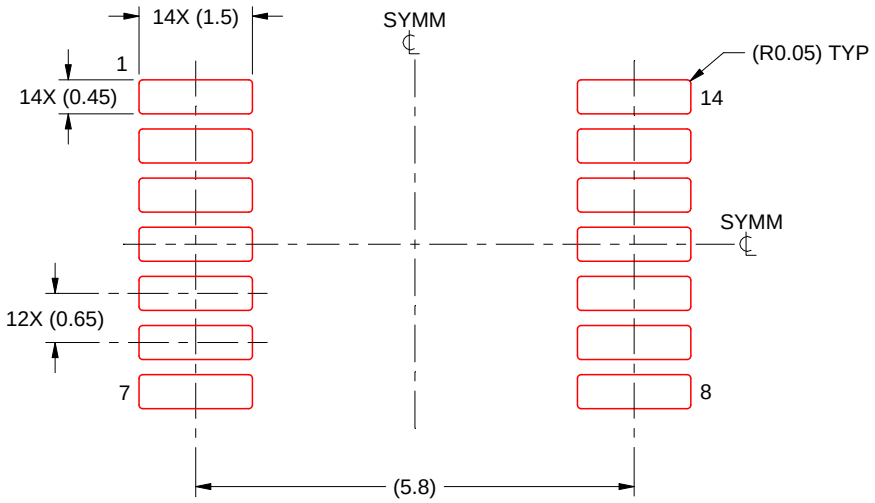


SOLDER MASK DETAILS

4220202/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

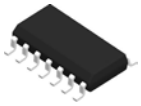


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

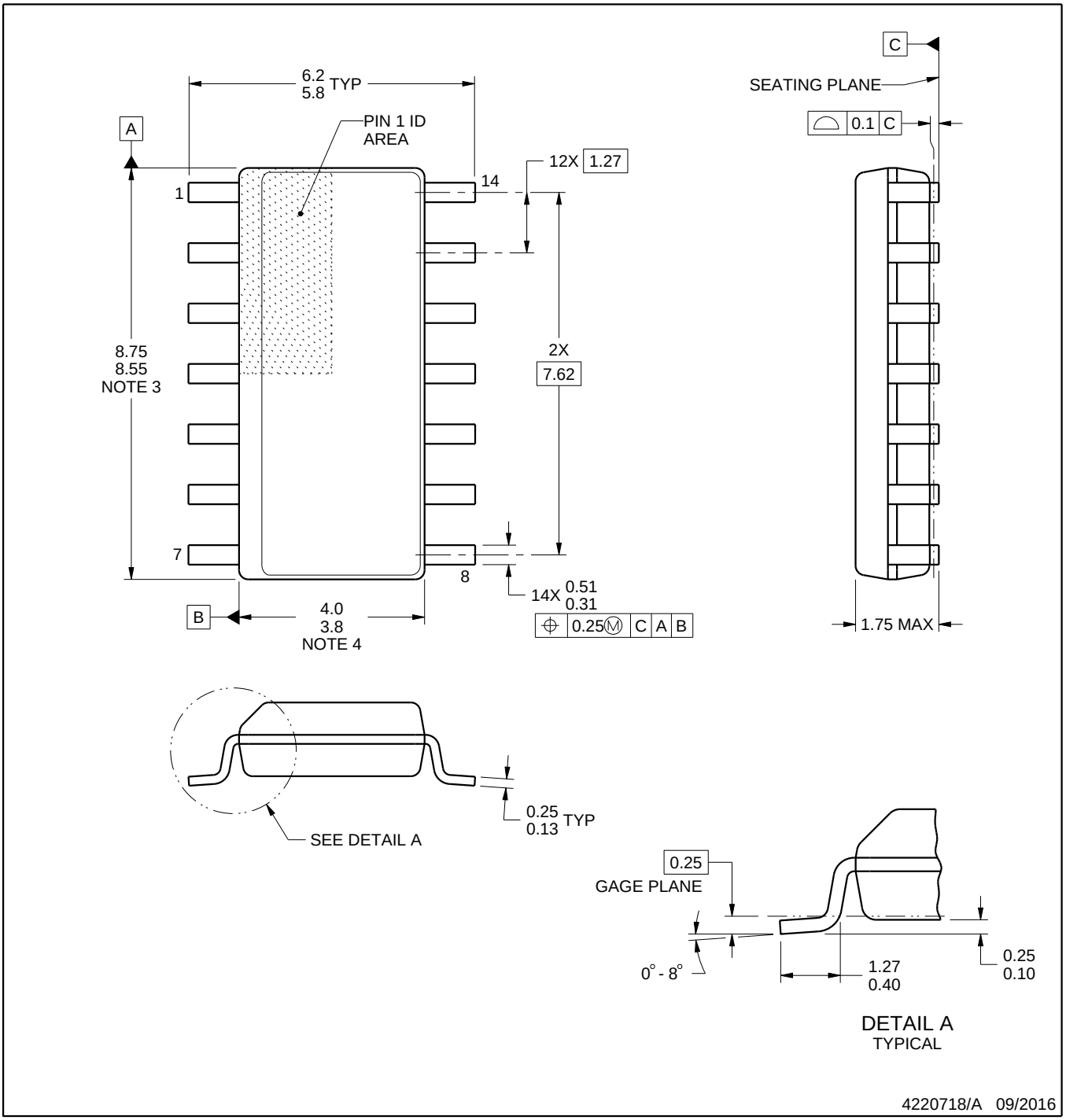


PACKAGE OUTLINE

D0014A

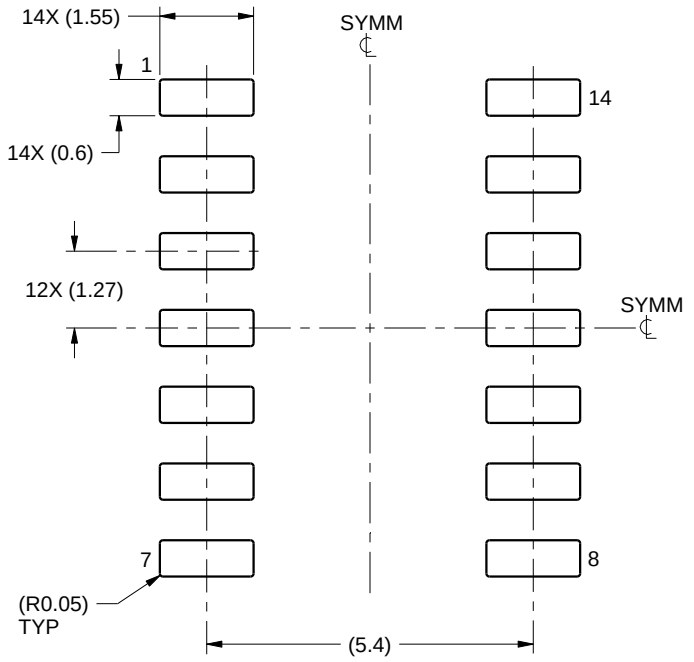
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

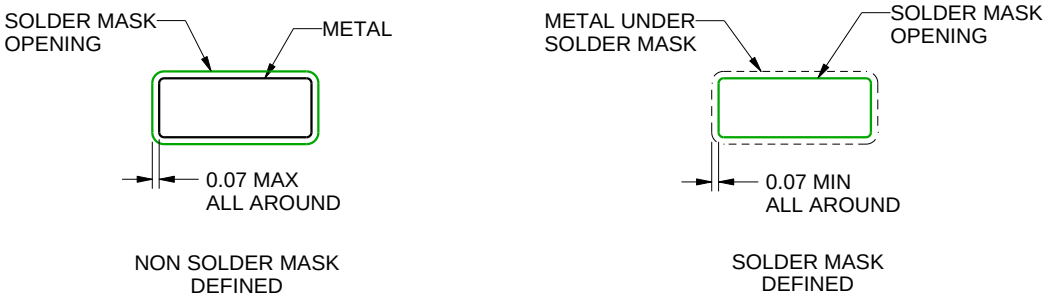


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
5. Reference JEDEC registration MS-012, variation AB.



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

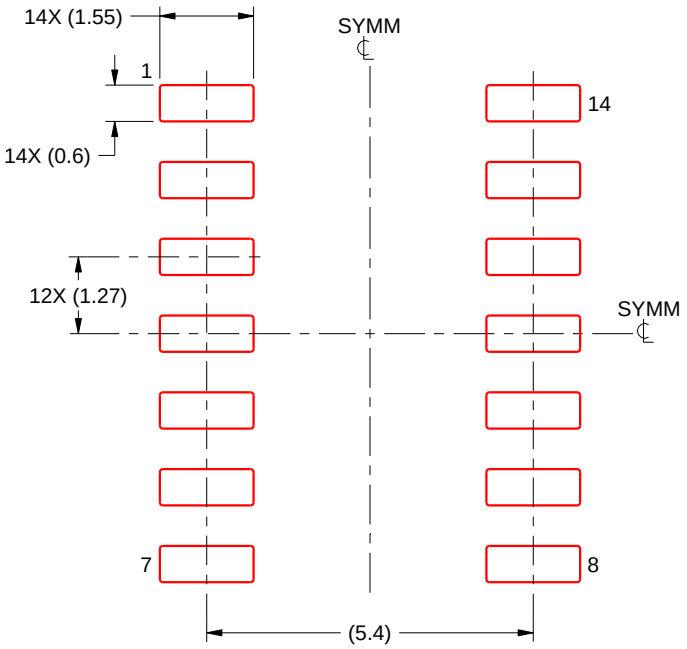
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



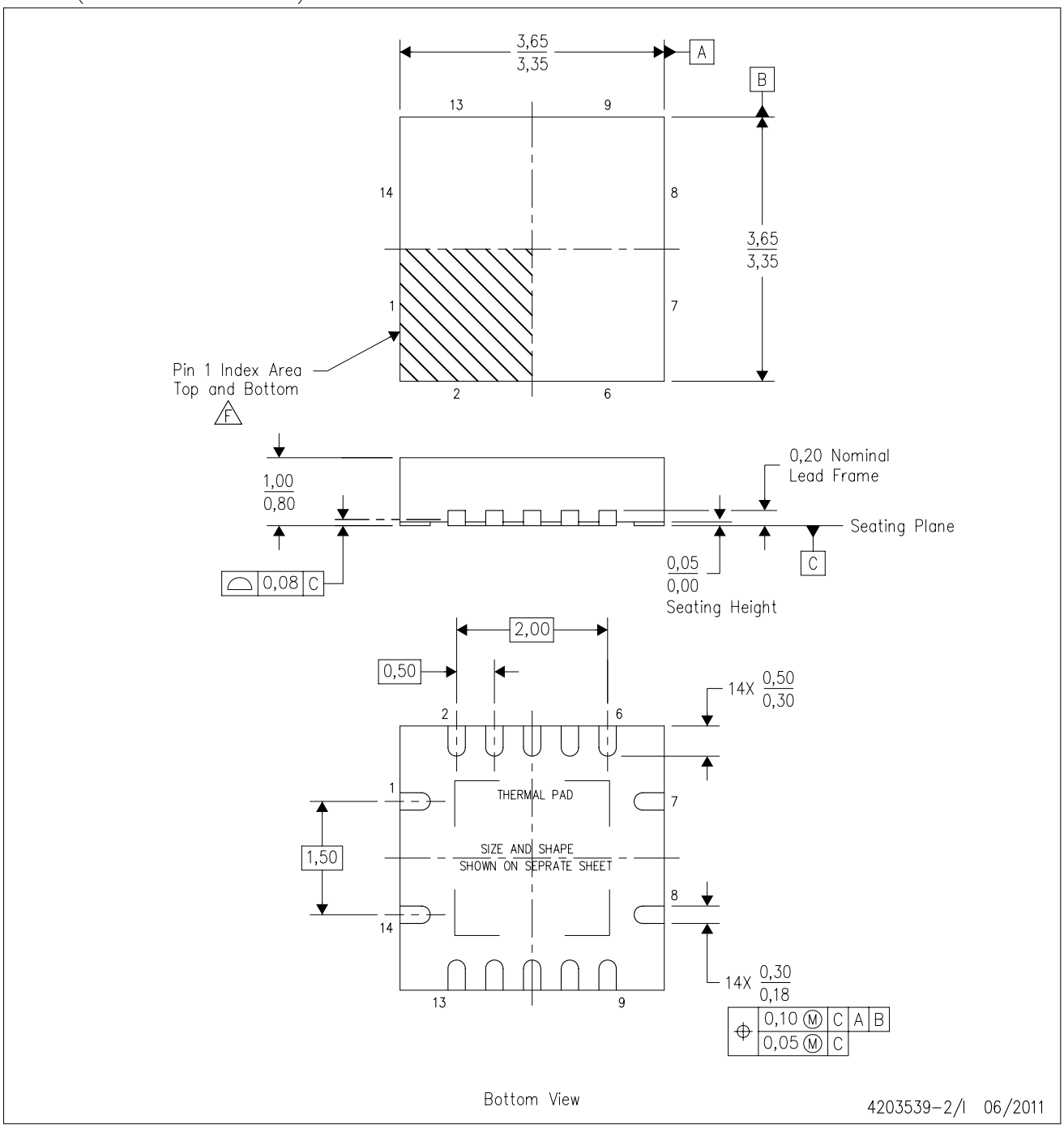
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

RGY (S–PVQFN–N14) PLASTIC QUAD FLATPACK NO–LEAD

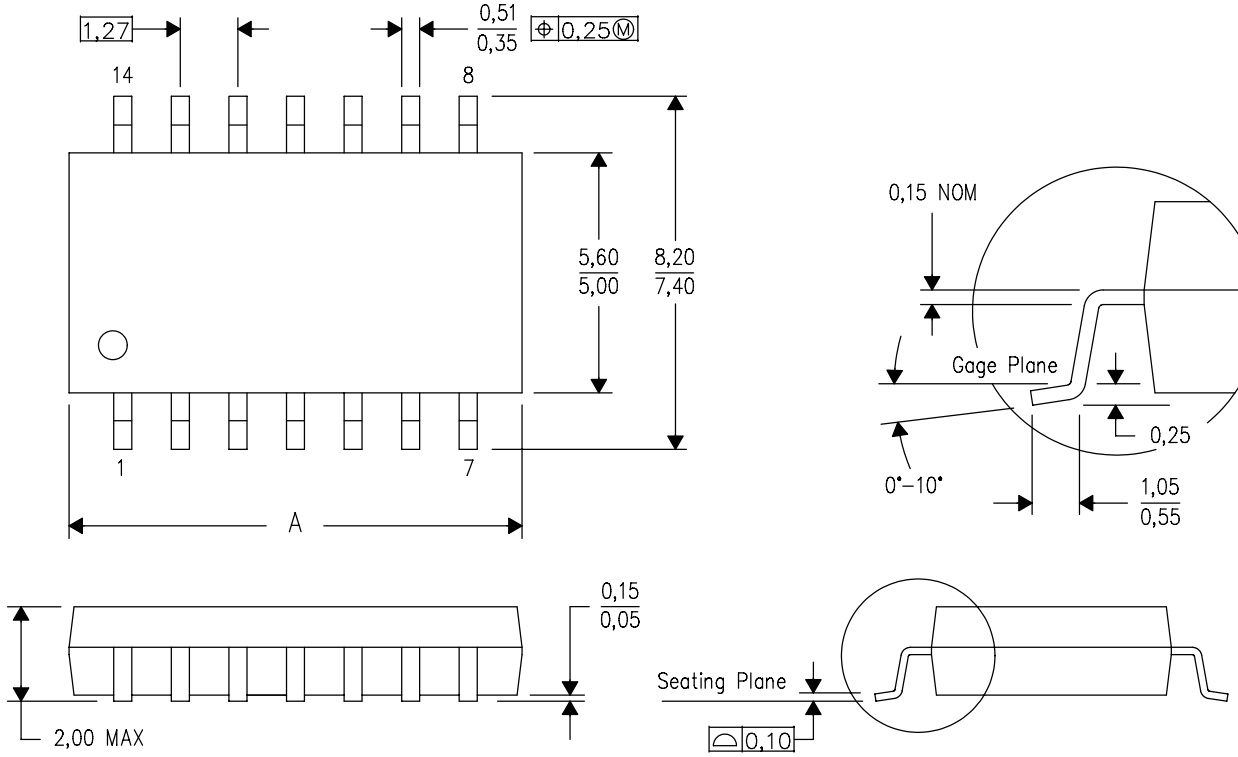


NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
G. Package complies to JEDEC MO–241 variation BA.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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